International

HEXFRED™

Features

- Ultrafast Recovery
- Ultrasoft Recovery
- Very Low I_{RRM}
- Very Low Q_{rr}
- Guaranteed Avalanche
- · Specified at Operating Conditions

Benefits

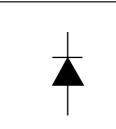
- Reduced RFI and EMI
- Reduced Power Loss in Diode and Switching Transistor
- Higher Frequency Operation
- Reduced Snubbing
- Reduced Parts Count

Description

International Rectifier's HFA15TB60 is a state of the art ultra fast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 volts and 8 amps per Leg continuous current, the HFA15TB60 is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultra fast recovery time, the HEXFRED product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the tb portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA15TB60 is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

Absolute Maximum Ratings

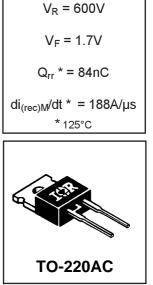
	Parameter	Max.	Units
V _R	Cathode-to-Anode Voltage	600	V
I _F @ T _C = 25°C	Continuous Forward Current		
I _F @ T _C = 100°C	Continuous Forward Current	15	А
I _{FSM}	Single Pulse Forward Current	150]
IFRM	Maximum Repetitive Forward Current	60	
E _{AS} ①	Maximum Single Pulse Avalanche Energy	28	mJ
I _{AR} @	Maximum Repetitive Avalanche Current	15	Α
P _D @ T _C = 25°C	Maximum Power Dissipation	74	w
P _D @ T _C = 100°C	Maximum Power Dissipation	29	7
TJ	Operating Junction and	-55 to +150	с
T _{STG}	Storage Temperature Range	-55 10 + 150	



HFA15TB60

PD -2.334

Ultrafast, Soft Recovery Diode



	Parameter	Min.	Тур.	Max.	Units	Test Conditions	
V _{BR}	Cathode Anode Breakdown Voltage	600			V	I _R = 100μA	
V _{FM}	Max Forward Voltage		1.3	1.7	V	I _F = 15A	
			1.5	2.0		I _F = 30A See Fig. 1	
			1.2	1.6		I _F = 15A, T _J = 125°C	
I _{RM}	Max Reverse Leakage Current		1.0	10	μA	V _R = V _R Rated See Fig. 2	
			400	1000		T _J = 125°C, V _R = 0.8 x V _R Rated	
CT	Junction Capacitance		25	50	рF	V _R = 200V See Fig. 3	
L _S	Series Inductance		8.0		nH	Measured lead to lead 5mm from	
						package body	

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

Dynamic Recovery Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Test Conditions		
t _{rr}	Reverse Recovery Time		19			$I_F = 1.0A, di_f/dt = 200A$	/µs, V _R = 30V	
t _{rr1}	See Fig. 5, 6 & 16		42	60	ns	T _J = 25°C		
t _{rr2}			74	120		T _J = 125°C	I _F = 15A	
I _{RRM1}	Peak Recovery Current See Fig. 7& 8		4.0	6.0	А	T _J = 25°C		
I _{RRM2}			6.5	10	~	T _J = 125°C	V _R = 200V	
Q _{rr1}	Reverse Recovery Charge See Fig. 9 & 10		84	180	nC $\frac{T_J = 25^{\circ}C}{T_J = 125^{\circ}C}$	T _J = 25°C	di _f /dt = 200A/µs	
Q _{rr2}			241	600		T _J = 125°C		
di _{(rec)M} /dt1	Peak Rate of Fall of Recovery Current		188		A/us	T _J = 25°C		
di _{(rec)M} /dt2	During t _b See Fig. 11 & 12		160		πµs	T _J = 125°C		

Thermal - Mechanical Characteristics

	Parameter	Min.	Тур.	Max.	Units
T _{lead} ③	Lead Temperature			300	°C
R _{θJC}	Thermal Resistance, Junction to Case			1.7	
R _{0JA} @	Thermal Resistance, Junction to Ambient			80	K/W
R _{0CS} S	Thermal Resistance, Case to Heat Sink		0.5]
Wt	Weight		2.0		g
	Weight		0.07		(oz)
Т	Mounting Torque	6.0		12	Kg-cm
		5.0		10	lbf•in

③ 0.063 in. from Case (1.6mm) for 10 sec

Typical Socket Mount

(5) Mounting Surface, Flat, Smooth and Greased

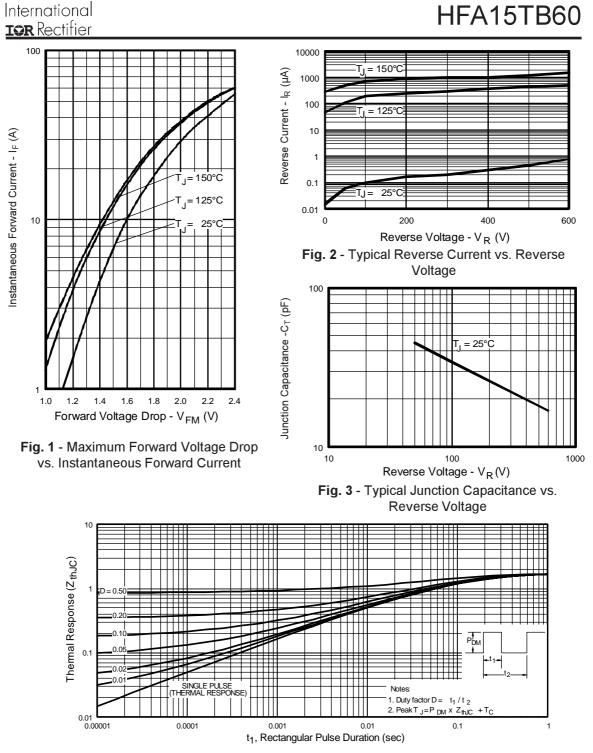


Fig. 4 - Maximum Thermal Impedance $\mathsf{Z}_{\mathsf{thjc}}$ Characteristics

International **tor** Rectifier

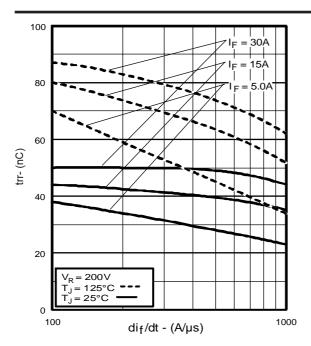


Fig. 5 - Typical Reverse Recovery vs. di_f/dt

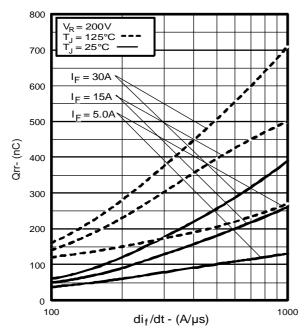


Fig. 7 - Typical Stored Charge vs. dif/dt

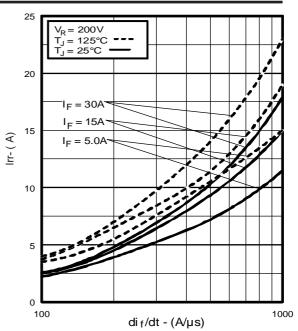
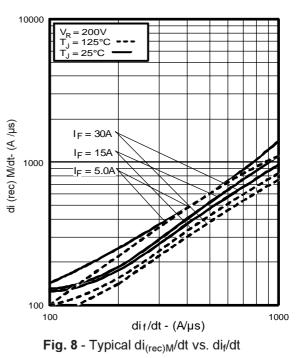
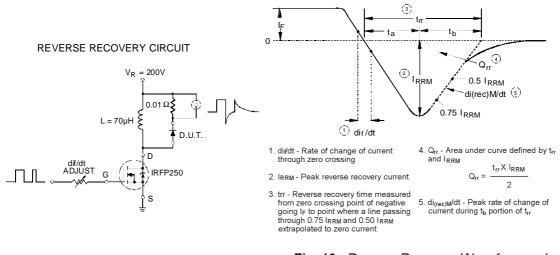
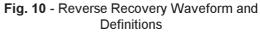


Fig. 6 - Typical Recovery Current vs. di_f/dt









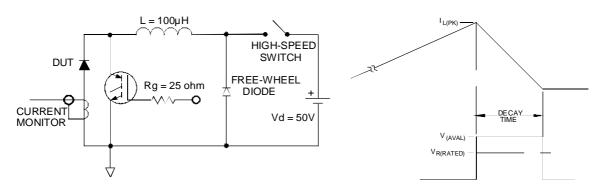
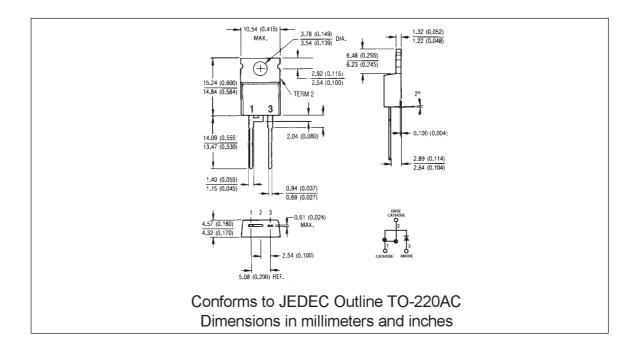


Fig. 11 - Avalanche Test Circuit and Waveforms



International

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 Data and specifications subject to change without notice.